

# 74F374

## Octal D-Type Flip-Flop with 3-STATE Outputs

### General Description

The 74F374 is a high-speed, low-power octal D-type flip-flop featuring separate D-type inputs for each flip-flop and 3-STATE outputs for bus-oriented applications. A buffered Clock (CP) and Output Enable ( $\overline{OE}$ ) are common to all flip-flops.

### Features

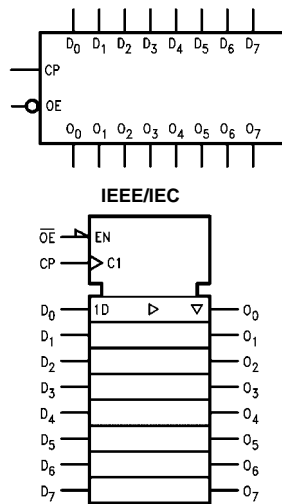
- Edge-triggered D-type inputs
- Buffered positive edge-triggered clock
- 3-STATE outputs for bus-oriented applications
- Guaranteed 4000V minimum ESD protection

### Ordering Code:

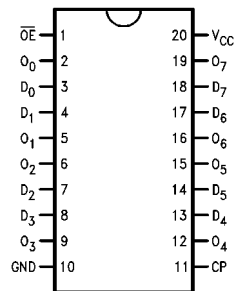
Order Number	Package Number	Package Description
74F374SC	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide
74F374SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74F374MSA	MSA20	20-Lead Shrink Small Outline Package (SSOP), EIAJ TYPE II, 5.3mm Wide
74F374PC	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300 Wide

Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

### Logic Symbols



### Connection Diagram



## Unit Loading/Fan Out

Pin Names	Description	U.L. HIGH/LOW	Input $I_{IH}/I_{IL}$ Output $I_{OH}/I_{OL}$
D <sub>0</sub> -D <sub>7</sub>	Data Inputs	1.0/1.0	20 $\mu$ A/-0.6 mA
CP	Clock Pulse Input (Active Rising Edge)	1.0/1.0	20 $\mu$ A/-0.6 mA
$\overline{OE}$	3-STATE Output Enable Input (Active LOW)	1.0/1.0	20 $\mu$ A/-0.6 mA
O <sub>0</sub> -O <sub>7</sub>	3-STATE Outputs	150/40 (33.3)	-3 mA/24 mA (20 mA)

## Functional Description

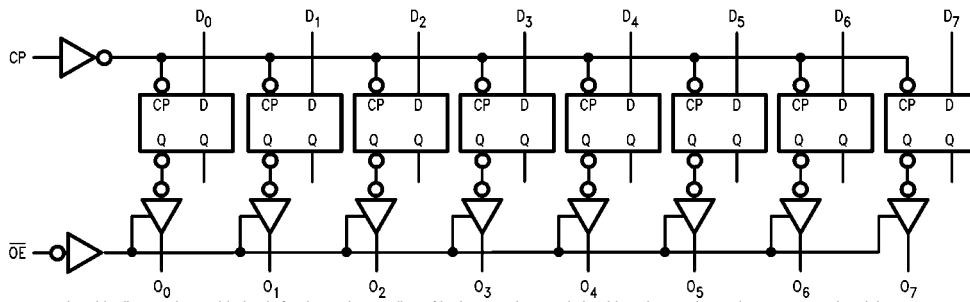
The 74F374 consists of eight edge-triggered flip-flops with individual D-type inputs and 3-STATE true outputs. The buffered clock and buffered Output Enable are common to all flip-flops. The eight flip-flops will store the state of their individual D inputs that meet the setup and hold time requirements on the LOW-to-HIGH Clock (CP) transition. With the Output Enable ( $\overline{OE}$ ) LOW, the contents of the eight flip-flops are available at the outputs. When the  $\overline{OE}$  is HIGH, the outputs go to the high impedance state. Operation of the  $\overline{OE}$  input does not affect the state of the flip-flops.

## Truth Table

Inputs			Internal Register	Output
D <sub>n</sub>	CP	$\overline{OE}$		O <sub>n</sub>
H	↗	L	H	H
L	↗	L	L	L
X	X	H	X	Z

H = HIGH Voltage Level  
 L = LOW Voltage Level  
 X = Immaterial  
 Z = High Impedance  
 ↗ = LOW-to-HIGH Clock Transition

## Logic Diagram



Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

**Absolute Maximum Ratings**(Note 1)

Storage Temperature	-65°C to +150°C
Ambient Temperature under Bias	-55°C to +125°C
Junction Temperature under Bias	-55°C to +150°C
V <sub>CC</sub> Pin Potential to Ground Pin	-0.5V to +7.0V
Input Voltage (Note 2)	-0.5V to +7.0V
Input Current (Note 2)	-30 mA to +5.0 mA
Voltage Applied to Output in HIGH State (with V <sub>CC</sub> = 0V)	
Standard Output	-0.5V to V <sub>CC</sub>
3-STATE Output	-0.5V to +5.5V
Current Applied to Output in LOW State (Max)	twice the rated I <sub>OL</sub> (mA)
ESD Last Passing Voltage (Min)	4000V

**Recommended Operating Conditions**

Free Air Ambient Temperature	0°C to +70°C
Supply Voltage	+4.5V to +5.5V

**Note 1:** Absolute maximum ratings are values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

**Note 2:** Either voltage limit or current limit is sufficient to protect inputs.

**DC Electrical Characteristics**

Symbol	Parameter	Min	Typ	Max	Units	V <sub>CC</sub>	Conditions
V <sub>IH</sub>	Input HIGH Voltage	2.0			V		Recognized as a HIGH Signal
V <sub>IL</sub>	Input LOW Voltage			0.8	V		Recognized as a LOW Signal
V <sub>CD</sub>	Input Clamp Diode Voltage			-1.2	V	Min	I <sub>IN</sub> = -18 mA
V <sub>OH</sub>	Output HIGH Voltage	10% V <sub>CC</sub>	2.5		V	Min	I <sub>OH</sub> = -1 mA
		10% V <sub>CC</sub>	2.4	I <sub>OH</sub> = -3 mA			
		5% V <sub>CC</sub>	2.7	I <sub>OH</sub> = -1 mA			
		5% V <sub>CC</sub>	2.7	I <sub>OH</sub> = -3 mA			
V <sub>OL</sub>	Output LOW Voltage	10% V <sub>CC</sub>		0.5	V	Min	I <sub>OL</sub> = 24 mA
I <sub>IH</sub>	Input HIGH Current			5.0	μA	Max	V <sub>IN</sub> = 2.7V
I <sub>BV1</sub>	Input HIGH Current Breakdown Test			7.0	μA	Max	V <sub>IN</sub> = 7.0V
I <sub>CEx</sub>	Output HIGH Leakage Current			50	μA	Max	V <sub>OUT</sub> = V <sub>CC</sub>
V <sub>ID</sub>	Input Leakage Test	4.75			V	0.0	I <sub>ID</sub> = 1.9 μA All Other Pins Grounded
I <sub>OD</sub>	Output Leakage Circuit Current			3.75	μA	0.0	V <sub>IOD</sub> = 150 mV All Other Pins Grounded
I <sub>IL</sub>	Input LOW Current			-0.6	mA	Max	V <sub>IN</sub> = 0.5V
I <sub>OZH</sub>	Output Leakage Current			50	μA	Max	V <sub>OUT</sub> = 2.7V
I <sub>OZL</sub>	Output Leakage Current			-50	μA	Max	V <sub>OUT</sub> = 0.5V
I <sub>OS</sub>	Output Short-Circuit Current	-60		-150	mA	Max	V <sub>OUT</sub> = 0V
I <sub>ZZ</sub>	Bus Drainage Test			500	μA	0.0V	V <sub>OUT</sub> = 5.25V
I <sub>CCZ</sub>	Power Supply Current		55	86	mA	Max	V <sub>O</sub> = HIGH Z

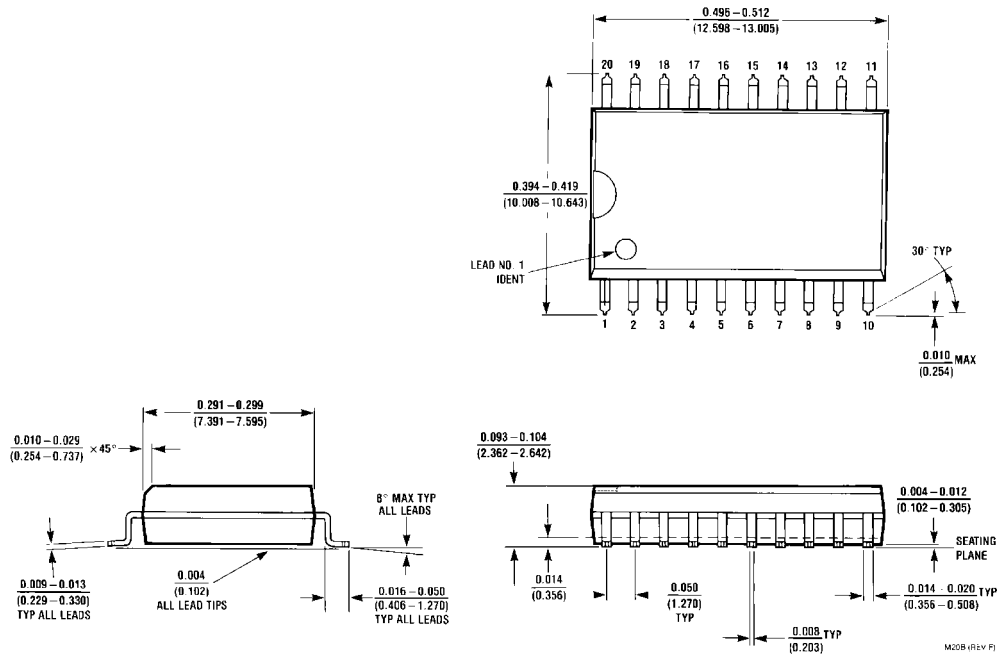
### AC Electrical Characteristics

Symbol	Parameter	$T_A = +25^\circ\text{C}$ $V_{CC} = +5.0\text{V}$ $C_L = 50\text{ pF}$			$T_A = -55^\circ\text{C to } +125^\circ\text{C}$ $V_{CC} = +5.0\text{V}$ $C_L = 50\text{ pF}$		$T_A = 0^\circ\text{C to } +70^\circ\text{C}$ $V_{CC} = +5.0\text{V}$ $C_L = 50\text{ pF}$		Units
		Min	Typ	Max	Min	Max	Min	Max	
$f_{MAX}$	Maximum Clock Frequency	100	140		60		70		MHz
$t_{PLH}$	Propagation Delay	4.0	6.5	8.5	4.0	10.5	4.0	10.0	ns
$t_{PHL}$	CP to $O_n$	4.0	6.5	8.5	4.0	11.0	4.0	10.0	
$t_{PZH}$	Output Enable Time	2.0	9.0	11.5	2.0	14.0	2.0	12.5	ns
$t_{PZL}$		2.0	5.8	7.5	2.0	10.0	2.0	8.5	
$t_{PHZ}$	Output Disable Time	2.0	5.3	7.0	2.0	8.0	2.0	8.0	ns
$t_{PLZ}$		1.5	4.3	5.5	1.5	7.5	1.5	6.5	

### AC Operating Requirements

Symbol	Parameter	$T_A = +25^\circ\text{C}$ $V_{CC} = +5.0\text{V}$		$T_A = -55^\circ\text{C to } +125^\circ\text{C}$ $V_{CC} = +5.0\text{V}$		$T_A = 0^\circ\text{C to } +70^\circ\text{C}$ $V_{CC} = +5.0\text{V}$		Units
		Min	Max	Min	Max	Min	Max	
$t_S(H)$	Setup Time, HIGH or LOW	2.0		2.5		2.0		ns
$t_S(L)$	$D_n$ to CP	2.0		2.0		2.0		
$t_H(H)$	Hold Time, HIGH or LOW	2.0		2.0		2.0		ns
$t_H(L)$	$D_n$ to CP	2.0		2.5		2.0		
$t_W(H)$	CP Pulse Width	7.0		7.0		7.0		ns
$t_W(L)$	HIGH or LOW	6.0		6.0		6.0		

**Physical Dimensions** inches (millimeters) unless otherwise noted

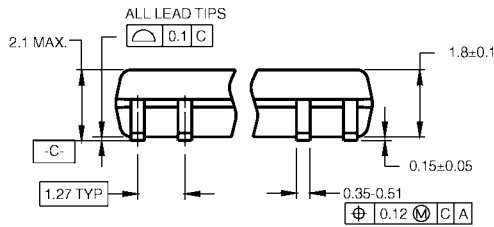


**20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300 Wide  
Package Number M20B**

**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)



LAND PATTERN RECOMMENDATION



DIMENSIONS ARE IN MILLIMETERS



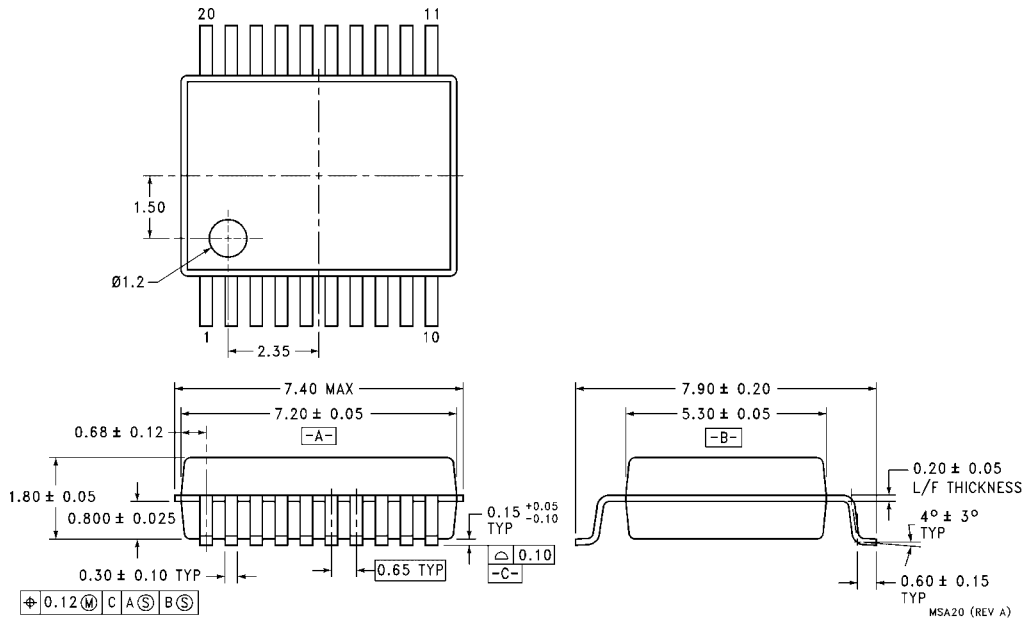
DETAIL A

- NOTES:  
 A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.  
 B. DIMENSIONS ARE IN MILLIMETERS.  
 C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.

M20DRevB1

**20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide Package Number M20D**

**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)



**20-Lead Shrink Small Outline Package (SSOP), EIAJ TYPE II, 5.3mm Wide  
Package Number MSA20**

